TOSHIBA Field Effect Transistor Silicon N Channel MOS Type

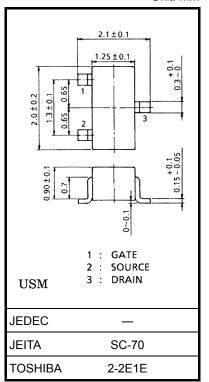
# SSM3K09FU

High Speed Switching Applications

- Small package
- Low on resistance
  - $: R_{on} = 0.7 \Omega (max) (@V_{GS} = 10 V)$
  - $: R_{on} = 1.2 \Omega (max) (@VGS = 4 V)$

#### Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-Source voltage		V <sub>DS</sub>	30	V	
Gate-Source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC	I <sub>D</sub>	400	mA	
	Pulse	I <sub>DP</sub>	800		
Drain power dissipation (Ta = $25^{\circ}$ C)		P <sub>D</sub> (Note 1)	150	mW	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature		T <sub>stg</sub>	-55~150	°C	



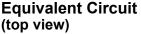
Weight: 0.006 g (typ.)

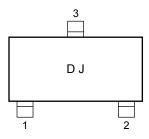
Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

> Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Mounted on FR4 board (25.4 mm  $\times$  25.4 mm  $\times$  1.6 t, Cu Pad: 0.6 mm  $^2$   $\times$  3) Figure 1.

#### Marking





## (top view)

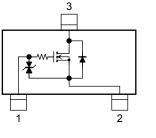
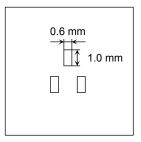


Figure 1: 25.4 mm  $\times$  25.4 mm  $\times$  1.6 t, Cu Pad:  $0.6 \text{ mm}^2 \times 3$ 



#### **Handling Precaution**

When handling individual devices (which are not yet mounting on a circuit board), be sure that the environment is protected against electrostatic electricity. Operators should wear anti-static clothing, and containers and other objects that come into direct contact with devices should be made of anti-static materials.

**Electrical Characteristics (Ta = 25°C)** 

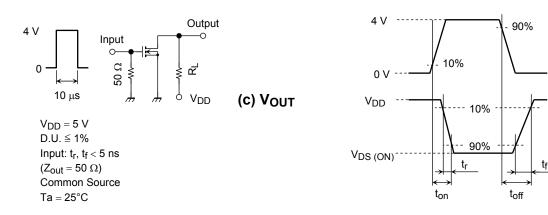
Chara	cteristics	Symbol	Test Condition		Min	Тур.	Max	Unit
Gate leakage curr	rent	I <sub>GSS</sub>	$V_{GS} = \pm 16 \text{ V}, \text{ V}_{DS} = 0$		_	_	±1	μA
Drain-Source brea	akdown voltage	V (BR) DSS	$I_D = 1 \text{ mA}, V_{GS} = 0$		30	_		V
Drain cut-off curre	ent	I <sub>DSS</sub>	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0$			_	1	μA
Gate threshold vo	Itage	V <sub>th</sub>	$V_{DS} = 5 \text{ V}, \text{ I}_{D} = 0.1 \text{ mA}$		1.1	_	1.8	V
Forward transfer a	admittance	Y <sub>fs</sub>	$V_{DS} = 5 \text{ V}, \text{ I}_{D} = 200 \text{ mA}$	(Note2)	270	_	_	mS
Drain-Source ON resistance		R <sub>DS (ON)</sub>	$I_D = 200 \text{ mA}, \text{ V}_{GS} = 10 \text{ V}$	(Note2)		0.5	0.7	Ω
			I <sub>D</sub> = 200 mA, V <sub>GS</sub> = 4 V	(Note2)		0.8	1.2	
			$I_D = 200 \text{ mA}, \text{ V}_{GS} = 3.3 \text{ V}$	(Note2)		1.0	1.7	
Input capacitance		C <sub>iss</sub>	$V_{DS}=5 \ V, \ V_{GS}=0, \ f=1 \ MHz$			20		pF
Reverse transfer capacitance		C <sub>rss</sub>	$V_{DS} = 5 \text{ V},  V_{GS} = 0,  f = 1  \text{MHz}$			7		pF
Output capacitance		C <sub>oss</sub>	$V_{DS} = 5 \text{ V},  V_{GS} = 0,  f = 1  \text{MHz}$			16		pF
Switching time	Turn-on time	t <sub>on</sub>	$V_{DD} = 5 \text{ V}, \text{ I}_{D} = 200 \text{ mA},$		_	72		ns
	Turn-off time	t <sub>off</sub>	$V_{GS} = 0 \sim 4 V$			68		ns

Note2: Pulse test

#### **Switching Time Test Circuit**

(a) Test circuit

(b) V<sub>IN</sub>



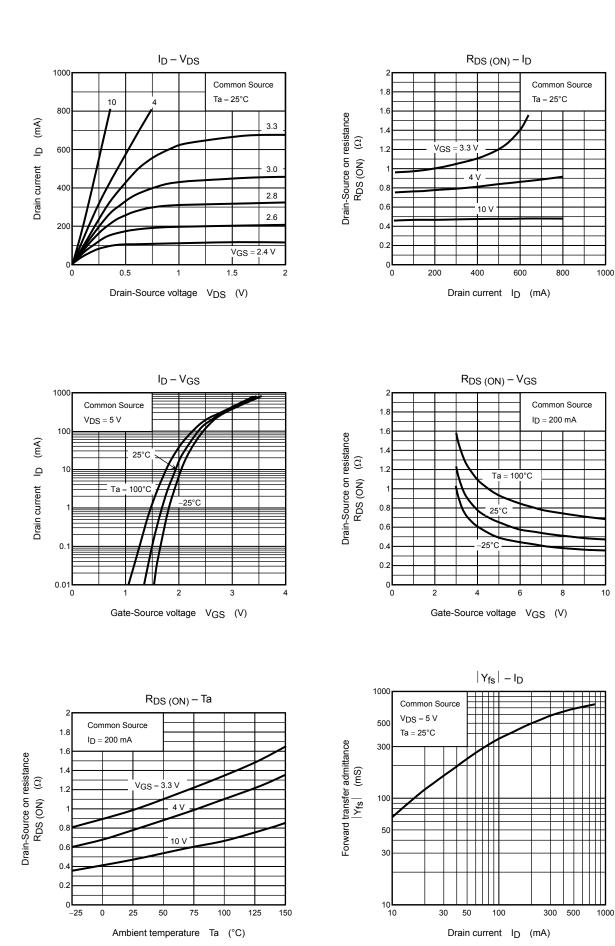
#### Precaution

 $V_{th}$  can be expressed as voltage between gate and source when low operating current value is  $I_D$  = 100  $\mu A$  for this product. For normal switching operation,  $V_{GS}$  (on) requires higher voltage than  $V_{th}$  and  $V_{GS}$  (off) requires lower voltage than  $V_{th}$ .

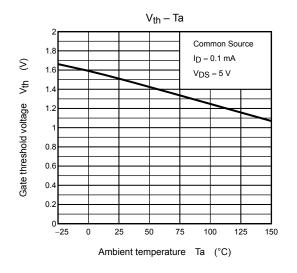
(relationship can be established as follows:  $V_{GS}$  (off) <  $V_{th}$  <  $V_{GS}$  (on) )

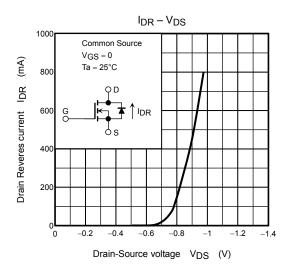
Please take this into consideration for using the device.

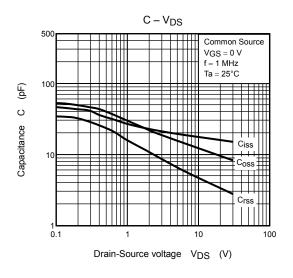
## **TOSHIBA**

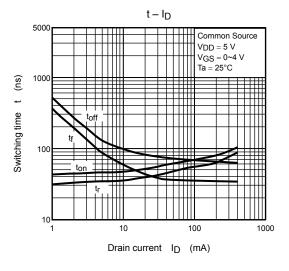


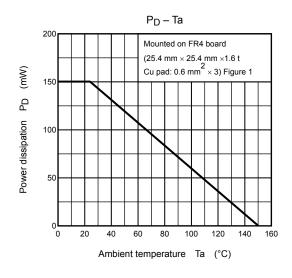
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20070701-EN GENERAL

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